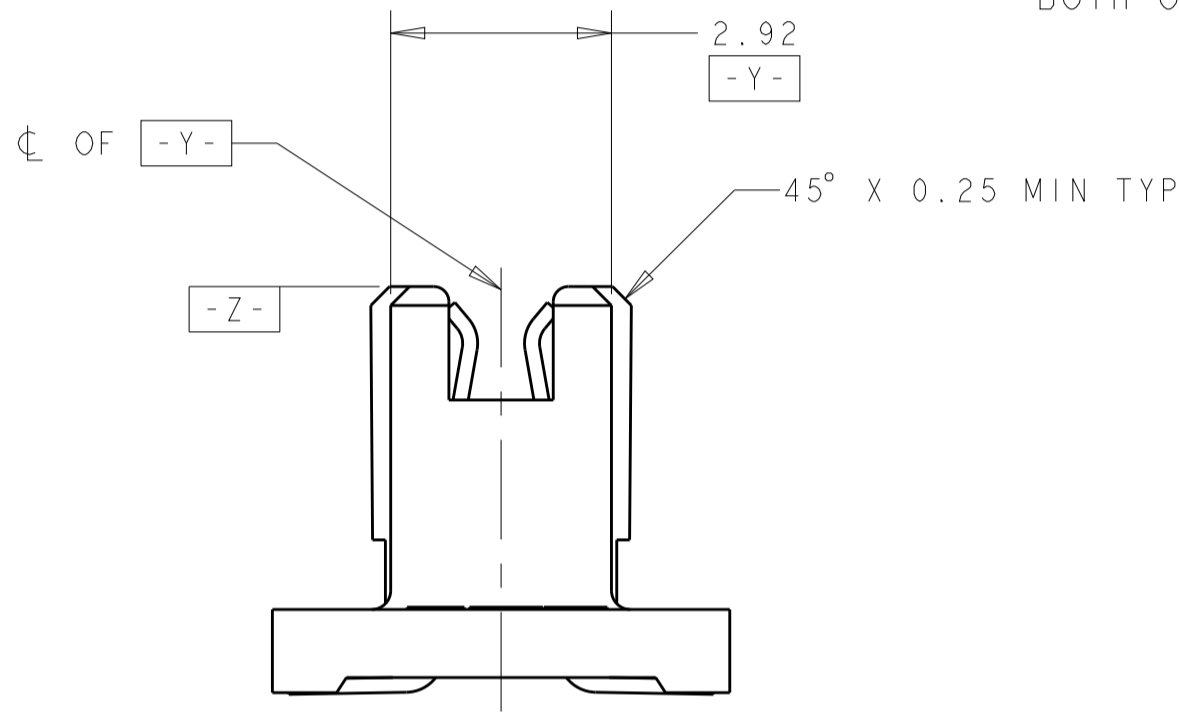
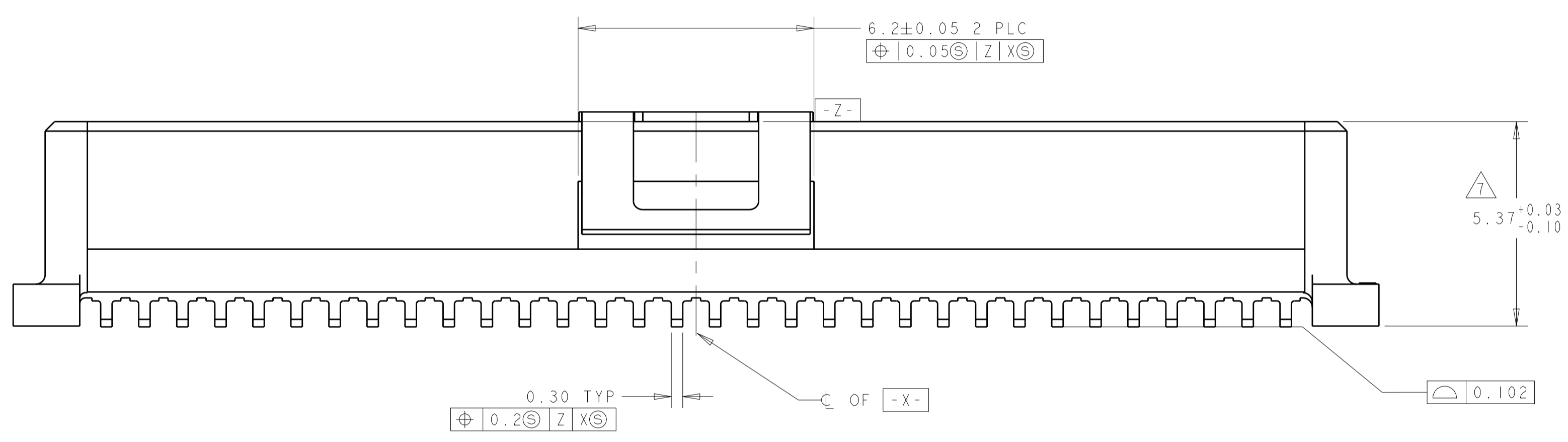
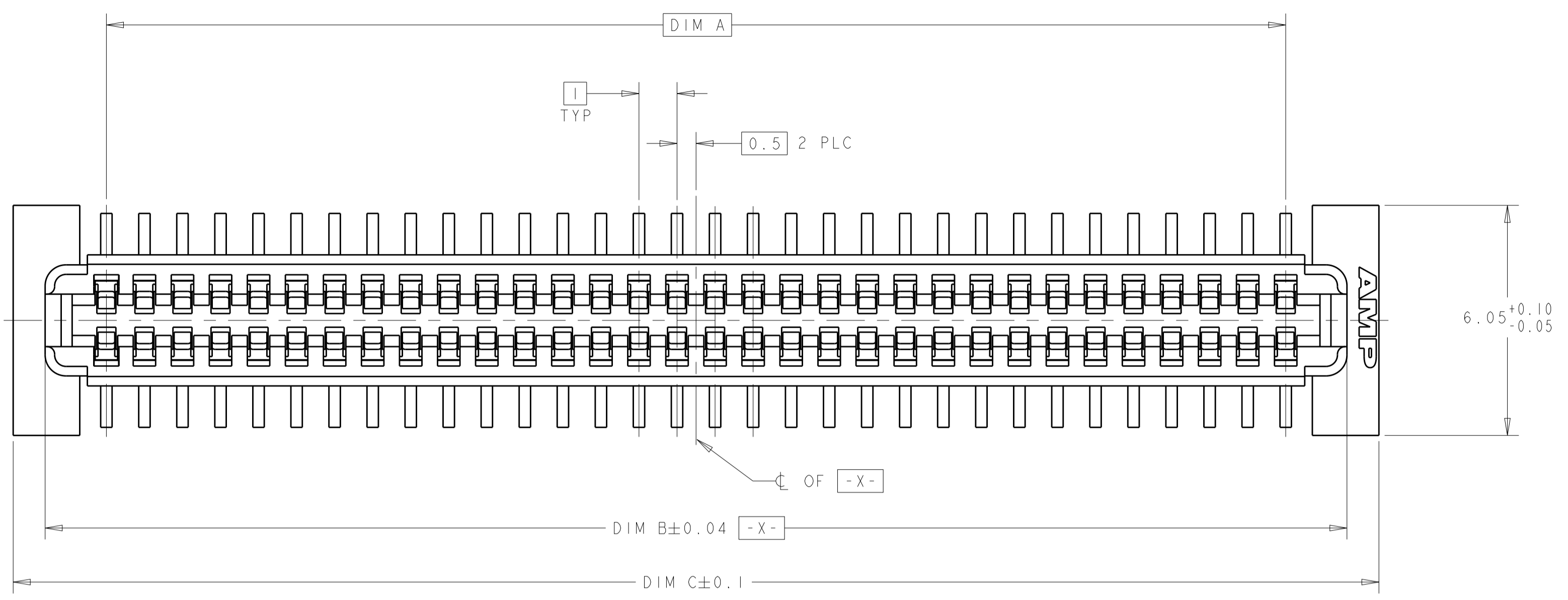
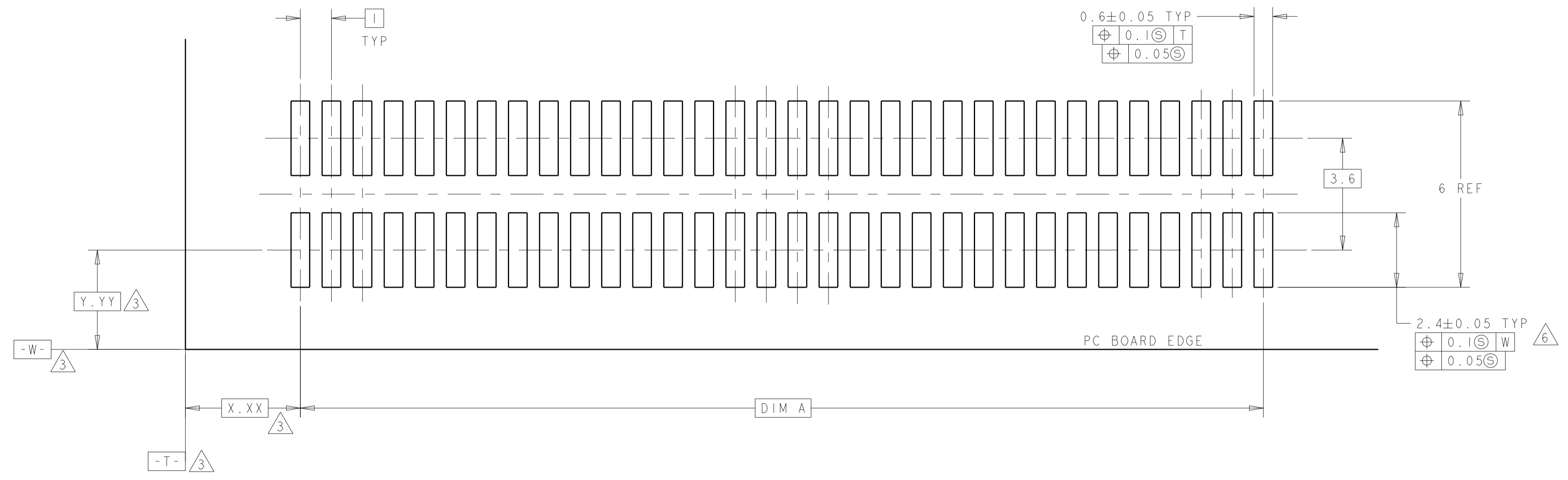
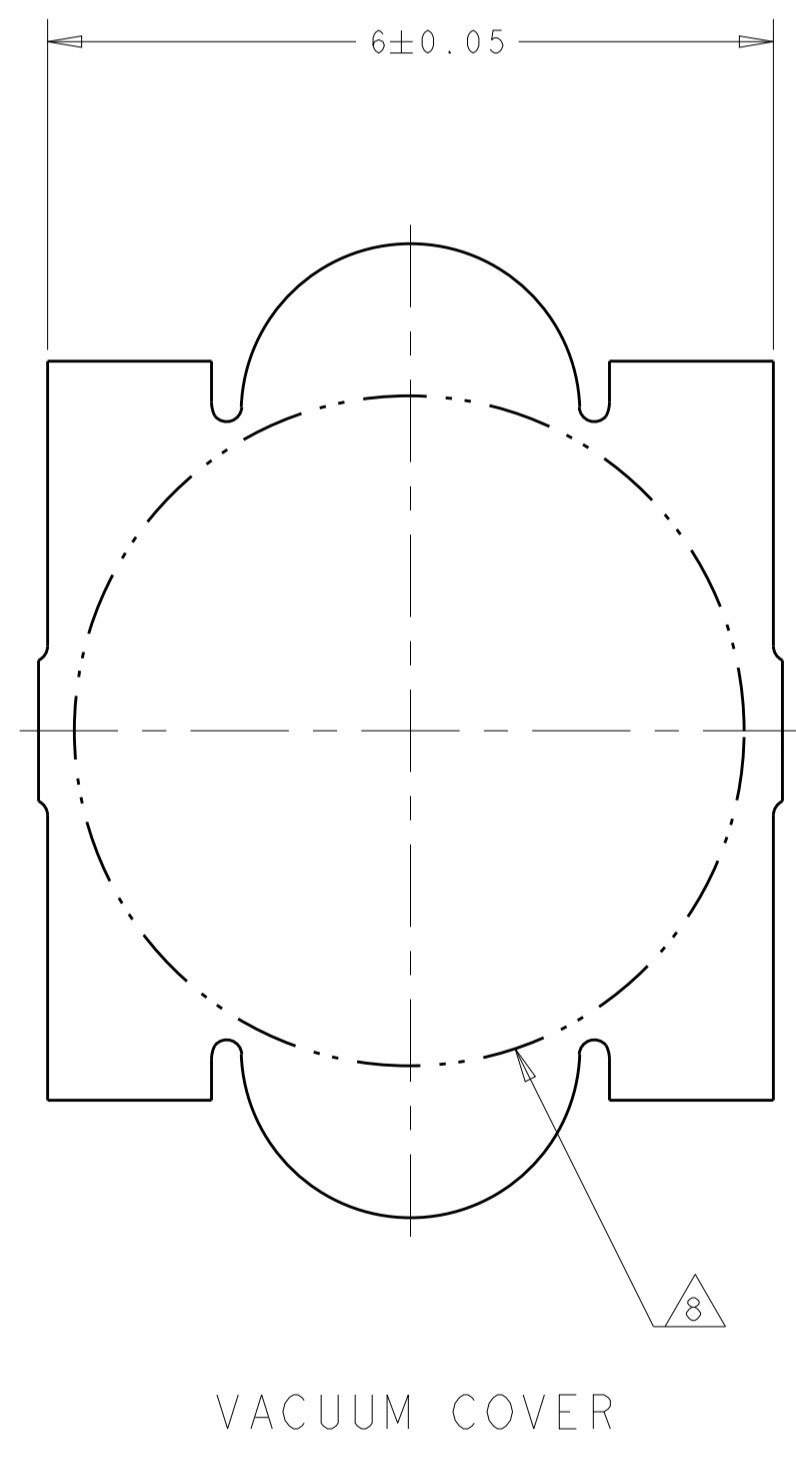


REVISIONS				
P.	LTN	DESCRIPTION	DATE	OWN APVD
L		REVISED PER ECR-14-016951	11FEB2015	J.T. W.H



- 1 HOUSING MATERIAL: HIGH TEMPERATURE THERMOPLASTIC, COLOR: BLACK
CONTACT MATERIAL: PHOSPHOR BRONZE
- 2 CONTACT FINISH: NICKEL UNDERPLATE ALL OVER, MATING SURFACES
PLATED TO MEET PLI PERFORMANCE REQUIREMENTS OF INDUSTRY
SPECIFICATION EIA-700AAAB, SOLDER TAILS PLATED TIN-LEAD.
- 3 DATUM LOCATIONS AND BASIC DIMENSIONS TO BE ESTABLISHED BY THE
CUSTOMER. CONSULT AMP ENGINEERING WHEN PLACING MULTIPLE
CONNECTORS ON A PC BOARD.
- 4. PACKAGED IN TAPE ON REEL PER EIA-481.
- 5. VACUUM COVER DESIGNED FOR 4mm DIA. NOZZLE. COVER TO BE REMOVED
AFTER SOLDERING. COVER OMITTED FROM SOME VIEWS FOR DIMENSIONAL
CLARITY.
- 6 SHORTER SOLDER LANDS MAY BE USED PER EIA 700AAAB, HOWEVER 2.4
LENGTH ASSURES OPTIMUM SOLDER FILLET REGARDLESS OF
MANUFACTURER OF CONNECTOR.
- 7 REFERRED TO AS DIM H = 5.30±0.1 IN EIA 700AAAB SPECIFICATION.
- 8 5.5 MIN DIA TARGET AREA FOR VACUUM PICK-UP.
- 9 CONTACT FINISH: 0.002 MINIMUM BRIGHT TIN-LEAD (93-7)
ON SOLDER AREA, 0.00127 MINIMUM GOLD ON MATING AREA,
BOTH OVER 0.00127 MINIMUM NICKEL ON ENTIRE CONTACT.



RECOMMENDED PC BOARD LAYOUT

FINISH	DIM C	DIM B	DIM A	MATING CONNECTOR	STACK HGTS	POS	PART NO
9	45.9	44.22	41	120534-2	10	84	1-120528-2
9	45.9	44.22	41	120533-2	9	84	1-120528-2
9	45.9	44.22	41	120532-2	8	84	1-120528-2
9	35.9	34.22	31	120534-1	10	64	1-120528-1
9	35.9	34.22	31	120533-1	9	64	1-120528-1
9	35.9	34.22	31	120532-1	8	64	1-120528-1
2	45.9	44.22	41	120534-2	10	84	120528-2
2	45.9	44.22	41	120533-2	9	84	120528-2
2	45.9	44.22	41	120532-2	8	84	120528-2
2	35.9	34.22	31	120534-1	10	64	120528-1
2	35.9	34.22	31	120533-1	9	64	120528-1
2	35.9	34.22	31	120532-1	8	64	120528-1

THIS DRAWING IS A CONTROLLED DOCUMENT. DWN: J. REED 27/11/97
CHK: L. VO 27/11/97

TE Connectivity

RCPT ASSY, W/COVER, 1.0mmFH (IEEE1386)
CONNECTOR

PRODUCT SPEC: 502-1079
APPLICATION SPEC: 114-25045

SCALE: 10:1 SHEET: 1 OF 1